

DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATIONATTORNEY DOCKET NO. 200208154-1

As a below named inventor, I hereby declare that:

My residence/post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**Solution-Processed Thin Film Transistor Formation Method**

the specification of which is attached hereto unless the following box is checked:

( ) was filed on \_\_\_\_\_ as US Application No. or PCT International Application  
Number \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understood the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56.

**Foreign Application(s) and/or Claim of Foreign Priority**

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor(s) certificate listed below and have also identified below any foreign application for patent or inventor(s) certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE FILED	PRIORITY CLAIMED UNDER 35 U.S.C. 119
			YES: _____ NO: _____
			YES: _____ NO: _____

**Provisional Application**

I hereby claim the benefit under Title 35, United States Code Section 119(e) of any United States provisional application(s) listed below:

APPLICATION NUMBER	FILING DATE

**U. S. Priority Claim**

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION NUMBER	FILING DATE	STATUS (patented/pending/abandoned)

**POWER OF ATTORNEY:**

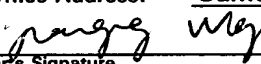
As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Customer Number **022879**Place Customer  
Number Bar Code  
Label hereSend Correspondence to:  
**HEWLETT-PACKARD COMPANY**  
Intellectual Property Administration  
P.O. Box 272400  
Fort Collins, Colorado 80527-2400

Direct Telephone Calls To:


**Larry D. Baker**  
**541 715 7331**

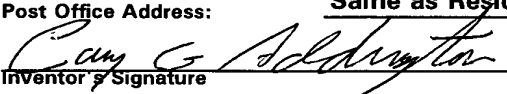
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Inventor: Jian-gang WengCitizenship: CNResidence: 2675 NW Garryanna Dr. #3 C rvallis, OR 97330Post Office Address: Same as ResidenceInventor's Signature Date 6/18/2003

**DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION (continued)**

ATTORNEY DOCKET NO. 200208154-1

Full Name of # 2 joint inventor: Ravi Prasad Citizenship: US  
Residence: 2870 NW Satinwood Street Corvallis, OR 97330  
Post Office Address: Same as residence  
Inventor's Signature  Date 16 June '03

Full Name of # 3 joint inventor: Cary G Addington Citizenship: US  
Residence: 2228 30th Avenue S.E. Albany, OR 97321 US  
Post Office Address: Same as Residence  
Inventor's Signature  Date June 25, 2003

Full Name of # 4 joint inventor: MAN HO CHEUNG Citizenship: SG  
Residence: Blk 257, #08-395, Jurong East st. 24 Singapore, Singapore 600257 Singapore  
Post Office Address: Same as Residence  
Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 5 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 6 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 7 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 8 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_  
Residence: \_\_\_\_\_  
Post Office Address: \_\_\_\_\_  
Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

**CONFIDENTIAL****WRITTEN AUTHORITY SOUGHT UNDER SECTION 34 OF THE PATENTS ACT (CAP. 221)****PART I (To be completed by the person seeking the request)**

*Name & Address of Person (s) (Inventor / Applicant / Others **)	:	Jian-gang Weng 2675 NW Garyanna Dr. #3 Corvallis, OR 97330 United States of America Citizenship: CN
*Name & Address of Person (s) (Inventor / Applicant / Others **)	:	Ravi Prasad 2870 NW Satinwood Street Corvallis, OR 97330 United States of America Citizenship: US
*Name & Address of Person (s) (Inventor / Applicant / Others **)	:	Cary G Addington 2228 30th Avenue S.E. Albany, OR 97321 United States of America Citizenship: US
*Name & Address of Person (s) (Inventor / Applicant / Others **)	:	Man Ho Cheung Blk 257 #08-395, Jurong East St 24 Singapore 600257 Singapore Citizenship: SG
Title of Invention	:	Solution-Processed Thin Film Transistor Formation Method
Country in which Protection is Sought	:	United States of America
Address for Service in Singapore	:	Intellectual Property, Asia Pacific Legal Department Hewlett-Packard Far East Pte Ltd 438A Alexandra Road #02-12 Alexandra Technopark Singapore 119967
Preferred Mode of Response from the Registrar (Please tick one of the following boxes and complete the corresponding blanks):		
<input checked="" type="checkbox"/> By Fax (Fax number is 6270 0885)		
<input type="checkbox"/> By Hand (To be collected by .....)		
<input type="checkbox"/> By normal, ordinary local mail.		
Contact No.	Telephone:	Pager:
	6374 8720	
Brief & Concise Description of the Invention (Use separate sheet)	See Abstract and Drawings attached	
Date of submission to the Registry of Patents (SG)	23 June 2003	

**PART II (To be completed by the Registry of Patents)**

With regard to the above matter received by the Registry, written authority is ☒ granted under Section 34 of the Patents Act (Cap. 221) to the above-mentioned applicant(s) and inventor(s) to file or cause to be filed the patent application outside Singapore for the invention mentioned in Part I.

23/06/2003  
Date

\* Attached additional sheet if necessary  
\*\* Delete as appropriate



KHONG JOKE CHAN (ASSISTANT REGISTRAR)  
Name & Signature

**DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION**ATTORNEY DOCKET NO. 200208154-1

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APPLICATION NUMBER	FILING DATE

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**POWER OF ATTORNEY:**

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Customer Number **022879**Place Customer  
Number Bar Code  
Label here

Send Correspondence to:  
**HEWLETT-PACKARD COMPANY**  
 Intellectual Property Administration  
 P.O. Box 272400  
 Fort Collins, Colorado 80527-2400

**Direct Telephone Calls To:**

**Larry D. Baker**  
**541 715 7331**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Inventor: Jian-gang WengCitizenship: CNResidence: 2675 NW Garryanna Dr. #3 Corvallis, OR 97330Post Office Address: Sam as Residence

Inventor's Signature \_\_\_\_\_

Date \_\_\_\_\_

**DECLARATION AND POWER OF ATTORNEY  
FOR PATENT APPLICATION (continued)**

ATTORNEY DOCKET NO. 200208154-1

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Residence: 2870 NW Satinwood Street Corvallis, OR 97330

Post Office Address: Same as residence

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 3 joint inventor: Cary G Addington Citizenship: US

Residence: 2228 30th Avenue S.E. Albany, OR 97321 US

Post Office Address: Same as Residence

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 4 joint inventor: MAN HO CHEUNG Citizenship: SG

Residence: Blk 257, #08-395, Jurong East st. 24 Singapore, Singapore 600257 Singapore

Post Office Address: Same as Residence

Inventor's Signature [Signature] Date 25 June 2003

Full Name of # 5 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 6 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 7 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_

Full Name of # 8 joint inventor: \_\_\_\_\_ Citizenship: \_\_\_\_\_

Residence: \_\_\_\_\_

Post Office Address: \_\_\_\_\_

Inventor's Signature \_\_\_\_\_ Date \_\_\_\_\_